

SOT1454-1

wafer level chip-scale package, 6 bumps

4 January 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP6
Package type industry code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	2-3-2016
Manufacturer package code	SOT1454

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.62	-	0.65	0.68	mm
E	package width	0.41	-	0.44	0.47	mm
A	seated height	0.24	-	0.27	0.3	mm
A ₂	package height	0.18	-	0.2	0.22	mm
e	nominal pitch	-	-	0.44	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

WLCSP6: wafer level chip-scale package, 6 bumps; 0.65 x 0.44 x 0.27 mm SOT1454-1

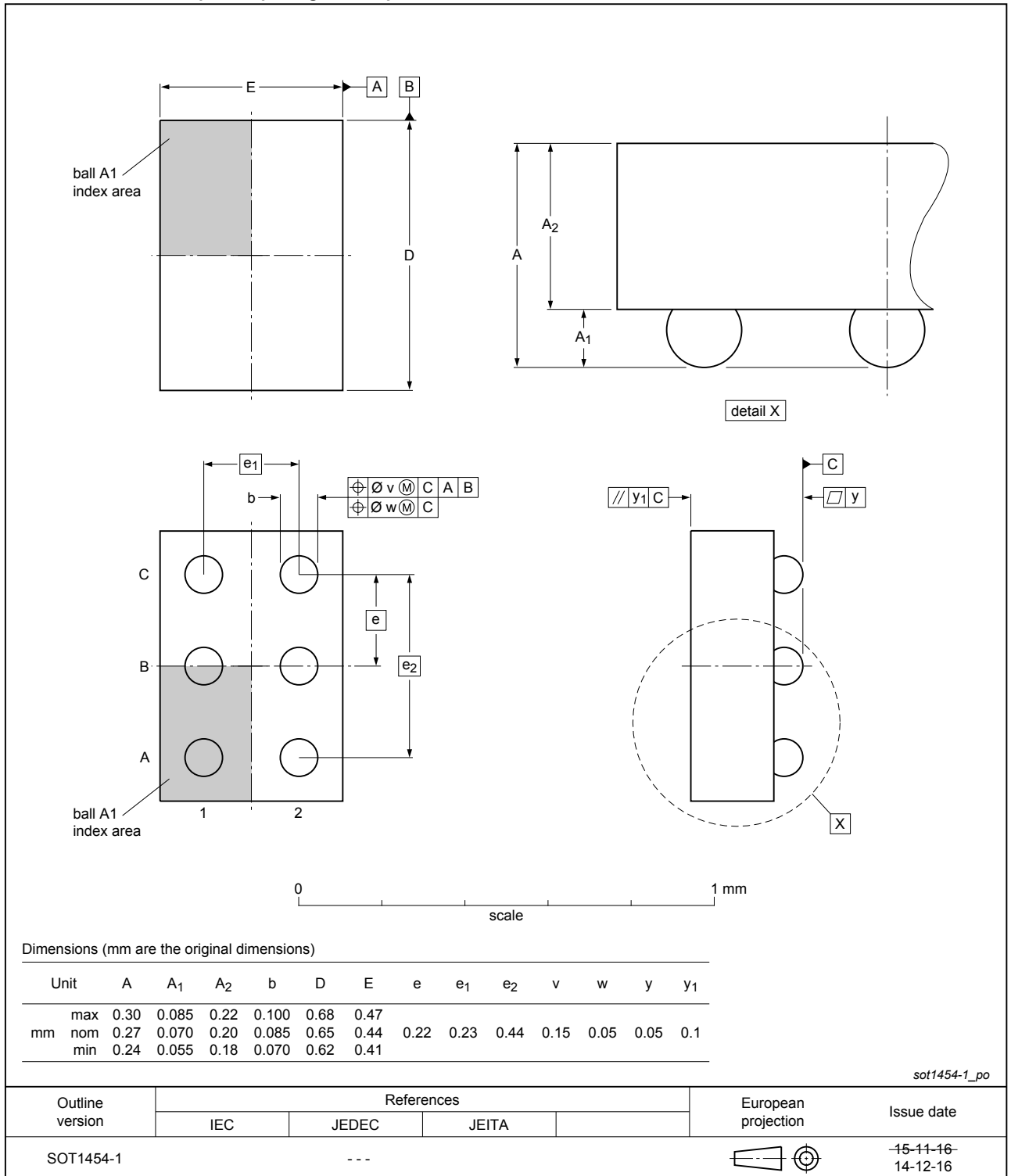


Fig. 1. Package outline WLCSP6 (SOT1454-1)

3. Legal information

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